

In the Specification

Please insert a paragraph after [0029] of the published application 2004/0055152 A1.

[0029.5] FIG. 8 shows a schematic illustrating multiple circuits on a sheet and the process of depaneling to separate the individual circuits.

Please amend paragraph [0011] as follows:

[0011] The copper/aluminum IMS laminates are typically imaged-and-etched in large panels to form to a plurality of the desired circuit pattern, as shown in FIG. 8. After the etching process, these panels are then cut into individual circuits by punching or scoring the aluminum base plate. To prevent chemical attack of the aluminum base plate during the copper etching process, masking and/or special process chemicals may be applied on the aluminum base plate. Care is taken during circuit processing and installation not to damage the epoxy dielectric layer because voids or "cracks" may lead to electrical shorting between the copper conductors and the aluminum base plate. Due to process considerations in both circuit manufacturing and depanelizing, the aluminum base plates used in IMS constructions are typically no more than about 0.125 inches thick. In addition, only planar aluminum base plates may be used for IMS constructions.